

74LCX00

Low Voltage Quad 2-Input NAND Gate with 5V Tolerant Inputs

Features

- 5V tolerant inputs
- 2.3V–3.6V V_{CC} specifications provided
- 5.2ns t_{PD} max. ($V_{CC} = 3.3V$), 10 μ A I_{CC} max.
- Power down high impedance inputs and outputs
- $\pm 24mA$ output drive ($V_{CC} = 3.0V$)
- Implements proprietary noise/EMI reduction circuitry
- Latch-up performance exceeds JEDEC 78 conditions
- ESD performance:
 - Human body model > 2000V
 - Machine model > 200V
- Leadless DQFN package

General Description

The LCX00 contains four 2-input NAND gates. The inputs tolerate voltages up to 7V allowing the interface of 5V systems to 3V systems.

The 74LCX00 is fabricated with advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.


Ordering Information

| Order Number | Package Number | Package Description |
|---------------------------|----------------|---|
| 74LCX00M | M14A | 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow |
| 74LCX00SJ | M14D | 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide |
| 74LCX00BQX ⁽¹⁾ | MLP14A | 14-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 3.0mm |
| 74LCX00MTC | MTC14 | 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide |

Note:

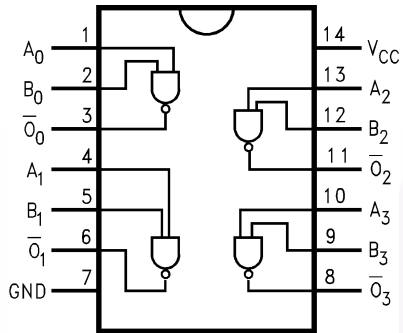
1. DQFN package available in Tape and Reel only.

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.

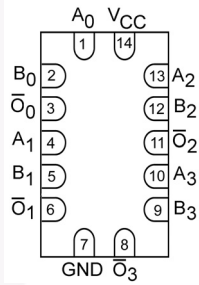
 All packages are lead free per JEDEC: J-STD-020B standard.

Connection Diagrams

Pin Assignments for SOIC, SOP, and TSSOP

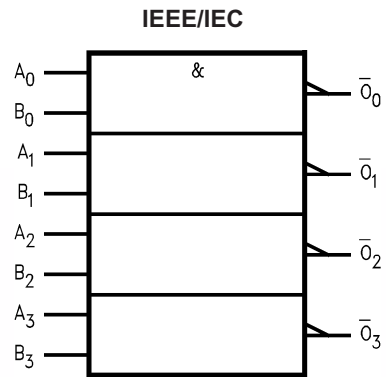


Pad Assignments for DQFN



(Top View)

Logic Symbol



Pin Description

| Pin Names | Description |
|------------------|-------------|
| A_n, B_n | Inputs |
| \overline{O}_n | Outputs |

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

| Symbol | Parameter | Rating |
|-----------|---|--------------------------|
| V_{CC} | Supply Voltage | -0.5V to +7.0V |
| V_I | DC Input Voltage | -0.5V to +7.0V |
| V_O | DC Output Voltage, Output in HIGH or LOW State ⁽²⁾ | -0.5V to $V_{CC} + 0.5V$ |
| I_{IK} | DC Input Diode Current, $V_I < GND$ | -50mA |
| I_{OK} | DC Output Diode Current $V_O < GND$ | -50mA |
| | $V_O > V_{CC}$ | +50mA |
| I_O | DC Output Source/Sink Current | $\pm 50mA$ |
| I_{CC} | DC Supply Current per Supply Pin | $\pm 100mA$ |
| I_{GND} | DC Ground Current per Ground Pin | $\pm 100mA$ |
| T_{STG} | Storage Temperature | -65°C to +150°C |

Note:

2. I_O Absolute Maximum Rating must be observed.

Recommended Operating Conditions⁽³⁾

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

| Symbol | Parameter | Min. | Max. | Units |
|-----------------------|---|------|----------|-------|
| V_{CC} | Supply Voltage Operating | 2.0 | 3.6 | V |
| | Data Retention | 1.5 | 3.6 | |
| V_I | Input Voltage | 0 | 5.5 | V |
| V_O | Output Voltage, HIGH or LOW State | 0 | V_{CC} | V |
| I_{OH} / I_{OL} | Output Current $V_{CC} = 3.0V-3.6V$ | | ± 24 | mA |
| | $V_{CC} = 2.7V-3.0V$ | | ± 12 | |
| | $V_{CC} = 2.3V-2.7V$ | | ± 8 | |
| T_A | Free-Air Operating Temperature | -40 | 85 | °C |
| $\Delta t / \Delta V$ | Input Edge Rate, $V_{IN} = 0.8V-2.0V$, $V_{CC} = 3.0V$ | 0 | 10 | ns/V |

Note:

3. Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

| Symbol | Parameter | V _{CC} (V) | Conditions | T _A = -40°C to +85°C | | Units |
|------------------|---------------------------------------|---------------------|--|---------------------------------|------|-------|
| | | | | Min. | Max. | |
| V _{IH} | HIGH Level Input Voltage | 2.3–2.7 | | 1.7 | | V |
| | | 2.7–3.6 | | 2.0 | | |
| V _{IL} | LOW Level Input Voltage | 2.3–2.7 | | | 0.7 | V |
| | | 2.7–3.6 | | | 0.8 | |
| V _{OH} | HIGH Level Output Voltage | 2.3–3.6 | I _{OH} = -100μA | V _{CC} - 0.2 | | V |
| | | 2.3 | I _{OH} = -8mA | 1.8 | | |
| | | 2.7 | I _{OH} = -12mA | 2.2 | | |
| | | 3.0 | I _{OH} = -18mA | 2.4 | | |
| | | | I _{OH} = -24mA | 2.2 | | |
| V _{OL} | LOW Level Output Voltage | 2.3–3.6 | I _{OL} = 100μA | | 0.2 | V |
| | | 2.3 | I _{OL} = 8mA | | 0.6 | |
| | | 2.7 | I _{OL} = 12mA | | 0.4 | |
| | | 3.0 | I _{OL} = 16mA | | 0.4 | |
| | | | I _{OL} = 24mA | | 0.55 | |
| I _I | Input Leakage Current | 2.3–3.6 | 0 ≤ V _I ≤ 5.5V | | ±5.0 | μA |
| I _{OFF} | Power-Off Leakage Current | 0 | V _I or V _O = 5.5V | | 10 | μA |
| I _{CC} | Quiescent Supply Current | 2.3–3.6 | V _I = V _{CC} or GND | | 10 | μA |
| | | | 3.6V ≤ V _I ≤ 5.5V | | ±10 | |
| ΔI _{CC} | Increase in I _{CC} per Input | 2.3–3.6 | V _{IH} = V _{CC} - 0.6V | | 500 | μA |

AC Electrical Characteristics

| Symbol | Parameter | T _A = -40°C to +85°C, R _L = 500Ω | | | | | | Units |
|---------------------------------------|--------------------------------------|---|------|--|------|---|------|-------|
| | | V _{CC} = 3.3V ± 0.3V, C _L = 50pF | | V _{CC} = 2.7V, C _L = 50pF | | V _{CC} = 2.5V ± 0.2V, C _L = 30pF | | |
| | | Min. | Max. | Min. | Max. | Min. | Max. | |
| t _{PHL} , t _{PLH} | Propagation Delay | 1.5 | 5.2 | 1.5 | 6.0 | 1.5 | 6.2 | ns |
| t _{OSSL} , t _{OSLH} | Output to Output Skew ⁽⁴⁾ | | 1.0 | | | | | ns |

Note:

4. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSSL}) or LOW-to-HIGH (t_{OSLH}).

Dynamic Switching Characteristics

| Symbol | Parameter | V_{CC} (V) | Conditions | $T_A = 25^\circ\text{C}$ | |
|-----------|--------------------------------------|--------------|---|--------------------------|------|
| | | | | Typical | Unit |
| V_{OLP} | Quiet Output Dynamic Peak V_{OL} | 3.3 | $C_L = 50\text{pF}$, $V_{IH} = 3.3\text{V}$, $V_{IL} = 0\text{V}$ | 0.8 | V |
| | | 2.5 | $C_L = 30\text{pF}$, $V_{IH} = 2.5\text{V}$, $V_{IL} = 0\text{V}$ | 0.6 | |
| V_{OLV} | Quiet Output Dynamic Valley V_{OL} | 3.3 | $C_L = 50\text{pF}$, $V_{IH} = 3.3\text{V}$, $V_{IL} = 0\text{V}$ | -0.8 | V |
| | | 2.5 | $C_L = 30\text{pF}$, $V_{IH} = 2.5\text{V}$, $V_{IL} = 0\text{V}$ | -0.6 | |

Capacitance

| Symbol | Parameter | Conditions | Typical | Units |
|-----------|-------------------------------|---|---------|-------|
| C_{IN} | Input Capacitance | $V_{CC} = \text{Open}$, $V_I = 0\text{V}$ or V_{CC} | 7 | pF |
| C_{OUT} | Output Capacitance | $V_{CC} = 3.3\text{V}$, $V_I = 0\text{V}$ or V_{CC} | 8 | pF |
| C_{PD} | Power Dissipation Capacitance | $V_{CC} = 3.3\text{V}$, $V_I = 0\text{V}$ or V_{CC} , $f = 10\text{MHz}$ | 25 | pF |

AC Loading and Waveforms (Generic for LCX Family)

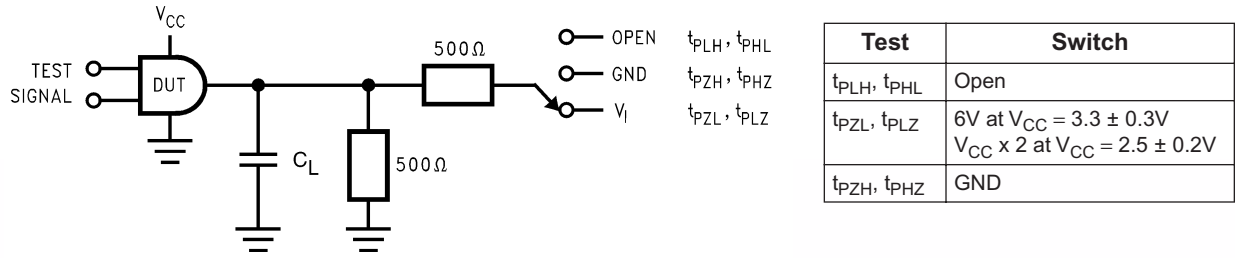
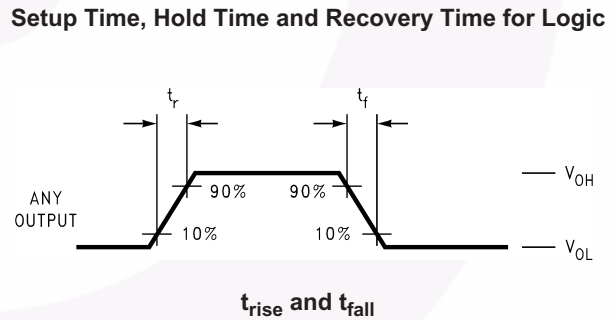
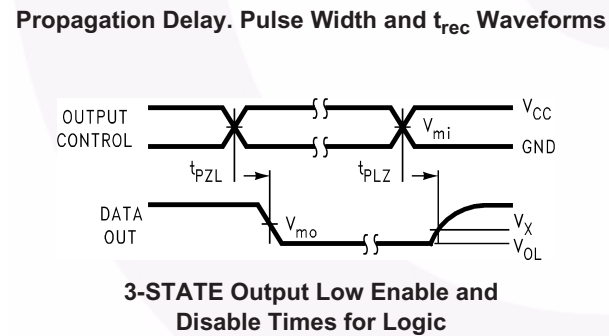
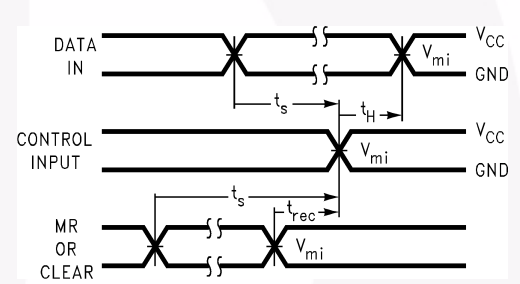
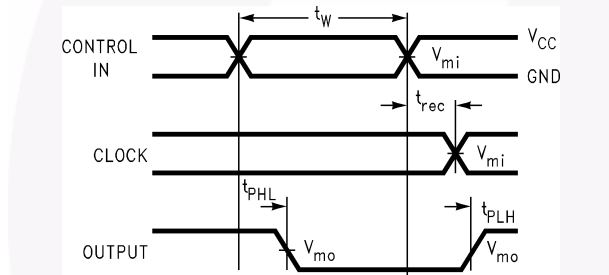
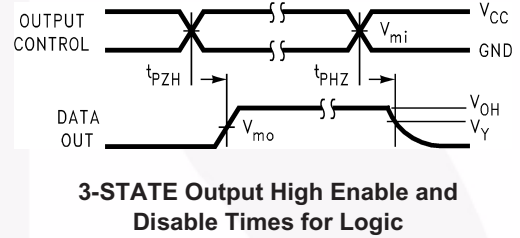
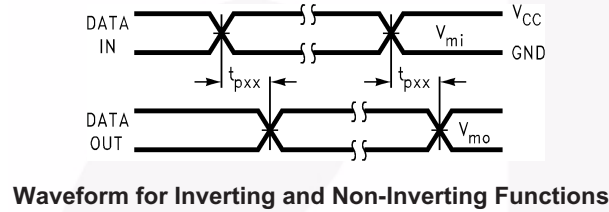


Figure 1. AC Test Circuit (C_L includes probe and jig capacitance)



| Symbol | V_{CC} | | |
|----------|-----------------|-----------------|------------------|
| | $3.3V \pm 0.3V$ | 2.7V | $2.5V \pm 0.2V$ |
| V_{mi} | 1.5V | 1.5V | $V_{CC}/2$ |
| V_{mo} | 1.5V | 1.5V | $V_{CC}/2$ |
| V_x | $V_{OL} + 0.3V$ | $V_{OL} + 0.3V$ | $V_{OL} + 0.15V$ |
| V_y | $V_{OH} - 0.3V$ | $V_{OH} - 0.3V$ | $V_{OH} - 0.15V$ |

Figure 2. Waveforms (Input Characteristics; $f = 1MHz, t_r = t_f = 3ns$)

Schematic Diagram (Generic for LCX Family)

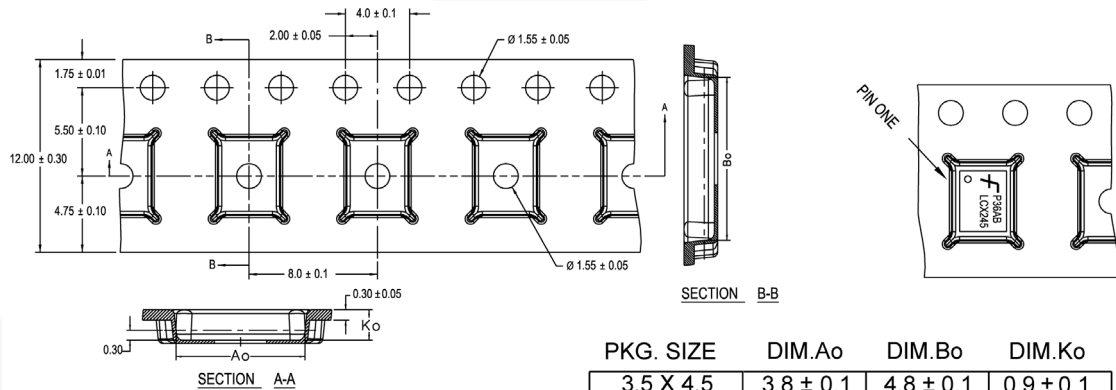


Tape and Reel Specification

Tape Format for DQFN

| Package Designator | Tape Section | Number of Cavities | Cavity Status | Cover Tape Status |
|--------------------|--------------------|--------------------|---------------|-------------------|
| BQX | Leader (Start End) | 125 (Typ.) | Empty | Sealed |
| | Carrier | 3000 | Filled | Sealed |
| | Trailer (Hub End) | 75 (Typ.) | Empty | Sealed |

Tape Dimensions inches (millimeters)



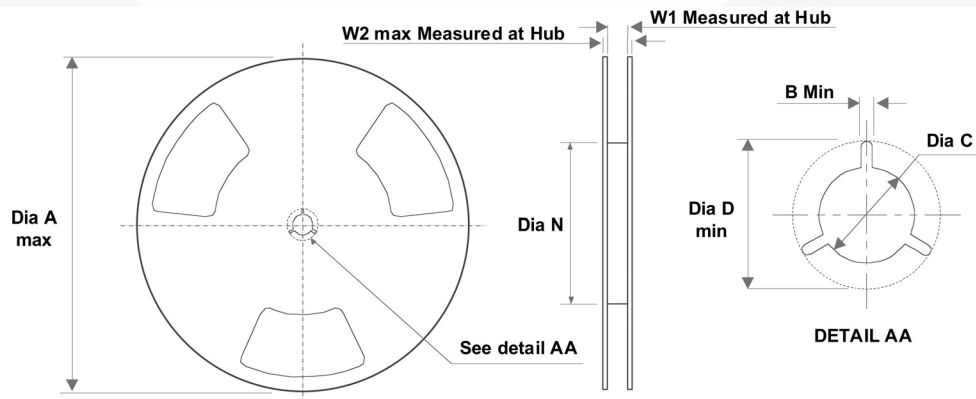
| PKG. SIZE | DIM.Ao | DIM.Bo | DIM.Ko |
|-----------|-----------|-----------|-----------|
| 3.5 X 4.5 | 3.8 ± 0.1 | 4.8 ± 0.1 | 0.9 ± 0.1 |
| 3.0 X 3.0 | 3.3 ± 0.1 | 3.3 ± 0.1 | 0.9 ± 0.1 |
| 2.5 X 4.5 | 2.8 ± 0.1 | 4.8 ± 0.1 | 0.9 ± 0.1 |
| 2.5 X 3.5 | 2.8 ± 0.1 | 3.8 ± 0.1 | 0.9 ± 0.1 |
| 2.5 X 3.0 | 2.8 ± 0.1 | 3.3 ± 0.1 | 0.9 ± 0.1 |
| 2.5 X 2.5 | 2.8 ± 0.1 | 2.8 ± 0.1 | 0.9 ± 0.1 |

DIMENSIONS ARE IN MILLIMETERS

NOTES: unless otherwise specified

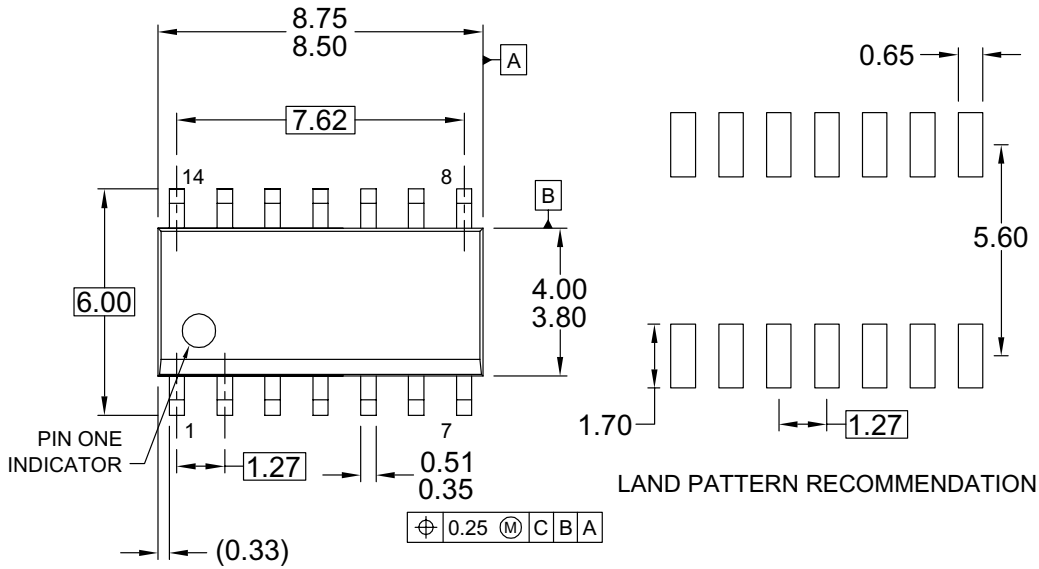
1. Cumulative pitch for feeding holes and cavities (chip pockets) not to exceed 0.008[0.20] over 10 pitch span.
2. Smallest allowable bending radius.
3. Thru hole inside cavity is centered within cavity.
4. Tolerance is $\pm 0.002[0.05]$ for these dimensions on all 12mm tapes.
5. Ao and Bo measured on a plane 0.120[0.30] above the bottom of the pocket.
6. Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
7. Pocket position relative to sprocket hole measured as true position of pocket. Not pocket hole.
8. Controlling dimension is millimeter. Dimension in inches rounded.

Reel Dimensions inches (millimeters)



| Tape Size | A | B | C | D | N | W1 | W2 |
|-----------|--------------|--------------|---------------|---------------|---------------|--------------|--------------|
| 12mm | 13.0 (330.0) | 0.059 (1.50) | 0.512 (13.00) | 0.795 (20.20) | 2.165 (55.00) | 0.488 (12.4) | 0.724 (18.4) |

Physical Dimensions



NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C,
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
- D) LANDPATTERN STANDARD: SOIC127P600X145-14M
- E) DRAWING CONFORMS TO ASME Y14.5M-1994
- F) DRAWING FILE NAME: M14AREV13



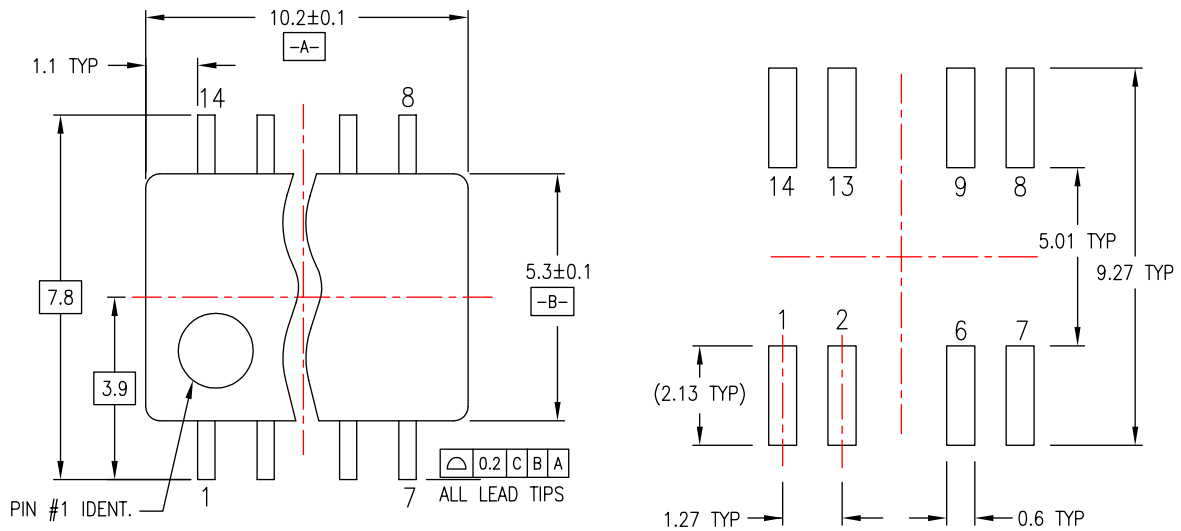
Figure 3. 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow

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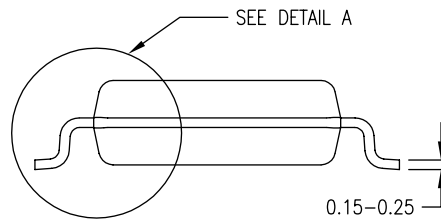
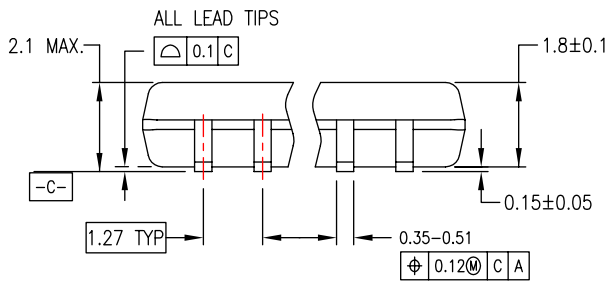
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Physical Dimensions (Continued)



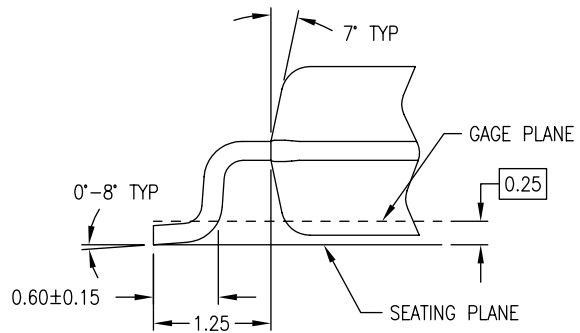
LAND PATTERN RECOMMENDATION



DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.



DETAIL A

M14DREVC

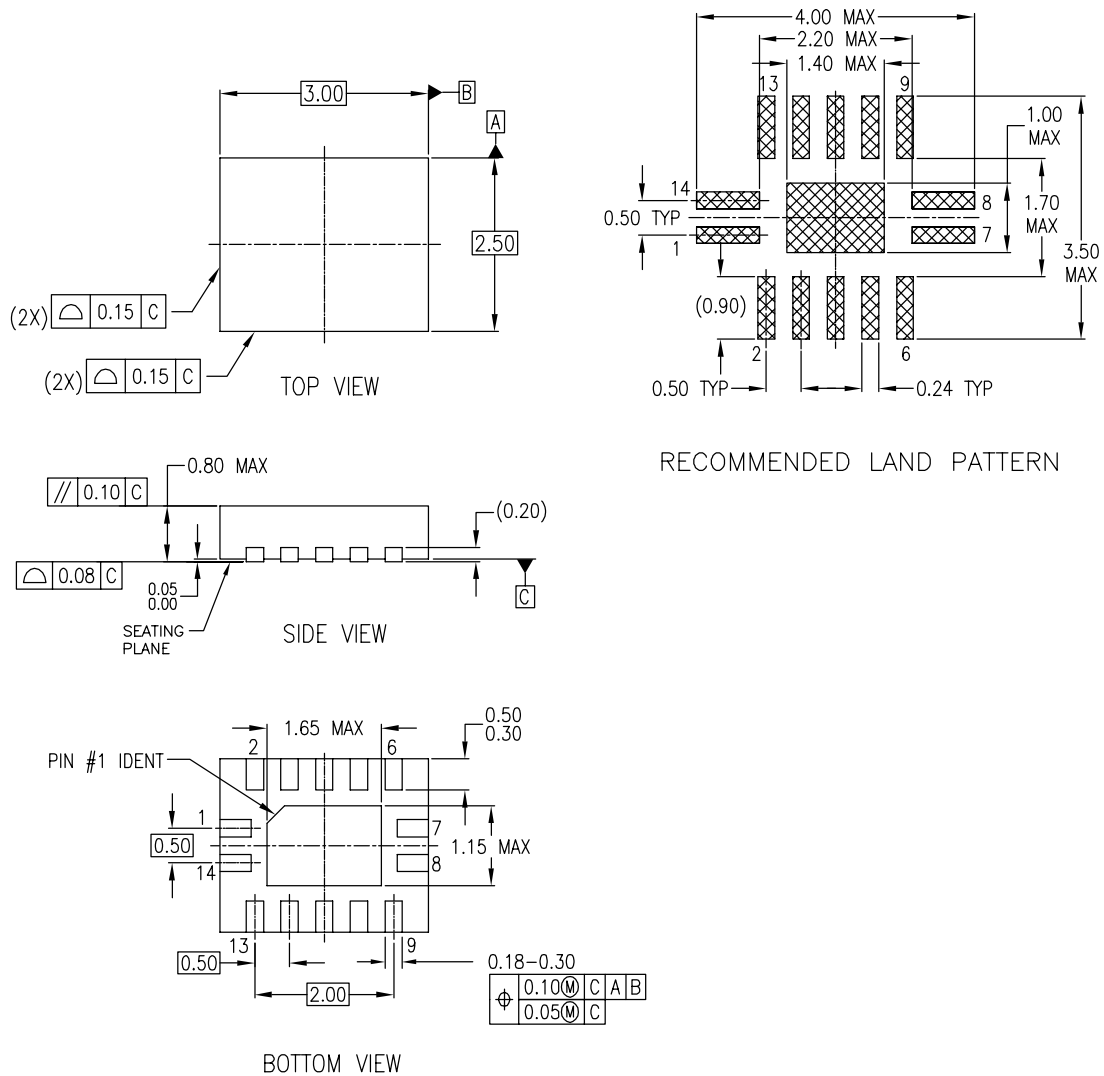
Figure 4. 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

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Physical Dimensions (Continued)



NOTES:

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- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994

MLP14ArevA

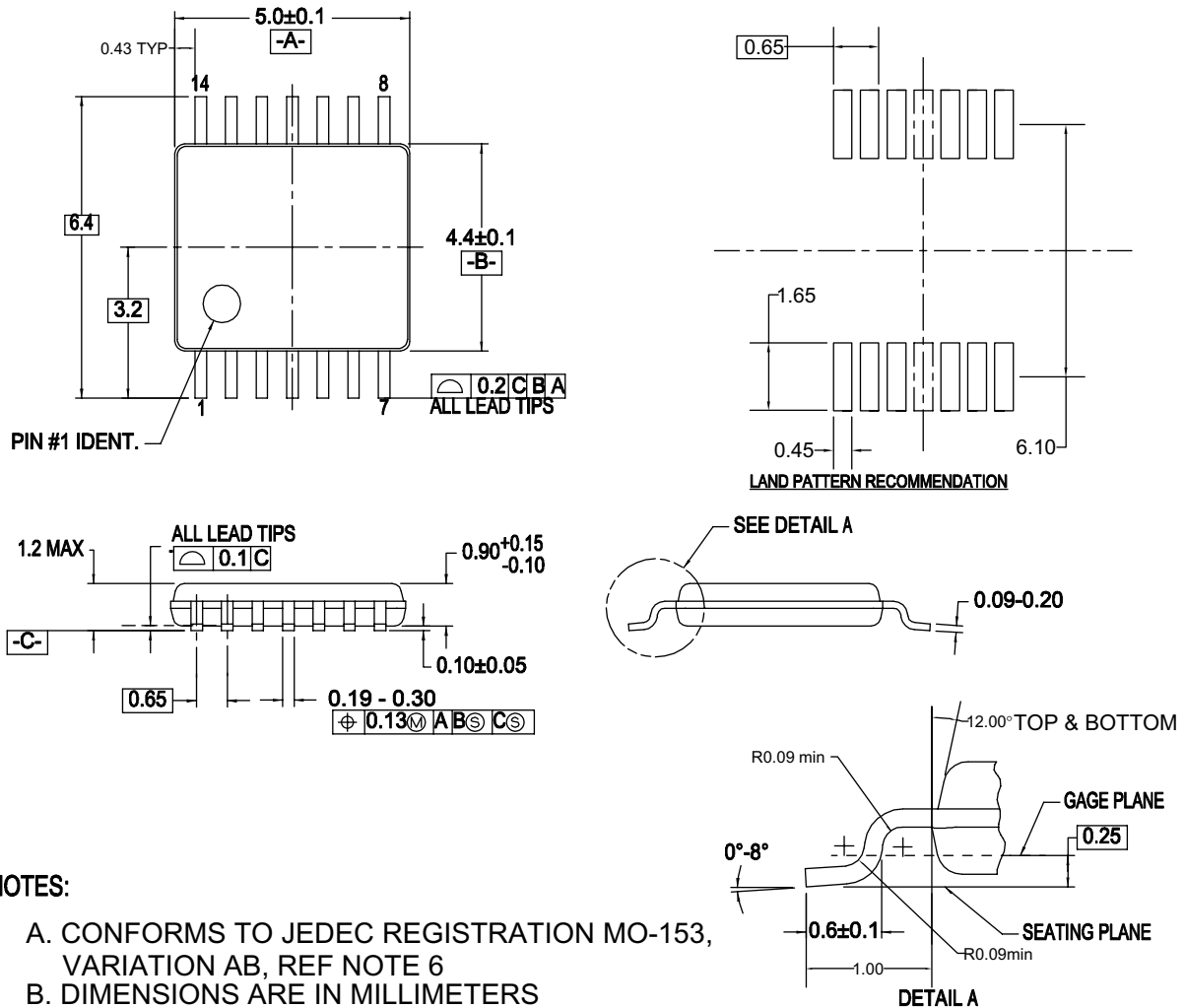
Figure 5. 14-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 3.0mm

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Physical Dimensions (Continued)



NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6
- B. DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
- D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1982
- E. LANDPATTERN STANDARD: SOP65P640X110-14M
- F. DRAWING FILE NAME: MTC14REV6

Figure 6. 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

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

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| FastvCore [™] | OPTOLOGIC [®] | SuperSOT [™] 3 | UHC [®] |
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